

C1206C562G2TACTU

Aliases (C1206C562G2TAC7800) SMD Comm X8G HT150C, Ceramic, 5,600 pF, 2%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1206, 1.5 mm



Click here for the 3D model.

| General Information | |
|--------------------------|--|
| Series | SMD Comm X8G HT150C |
| Style | SMD Chip |
| Description | SMD, MLCC, High Temperature, Ultra-Stable |
| Features | High Temperature, Ultra-Stable |
| RoHS | Yes |
| Termination | Tin |
| Marking | No |
| AEC-Q200 | No |
| Typical Component Weight | 15 mg |
| Shelf Life | 78 Weeks |
| MSL | 1 |

| Dimensions | |
|------------|------------------|
| Chip Size | 1206 |
| L | 3.2mm +/-0.2mm |
| W | 1.6mm +/-0.2mm |
| т | 0.78mm +/-0.10mm |
| S | 1.5mm MIN |
| В | 0.5mm +/-0.25mm |
| | |

Packaging Specifications Packaging

Packaging Quantity

T&R, 180mm, Plastic Tape 4000

| Specifications | |
|--|--|
| Capacitance | 5,600 pF |
| Measurement Condition | 1 kHz 1.0Vrms |
| Tolerance | 2% |
| Voltage DC | 200 VDC |
| Dielectric Withstanding Voltage | 500 VDC |
| Temperature Range | -55/+150°C |
| Temp. Coefficient | X8G |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 ppm/C, 1kHz 1.0Vrms |
| Dissipation Factor | 0.1%1 kHz 1.0Vrms |
| Aging Rate | 0% Loss/Decade Hour: Referee Time is 1000 Hours |
| Insulation Resistance | 100 GOhms |

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